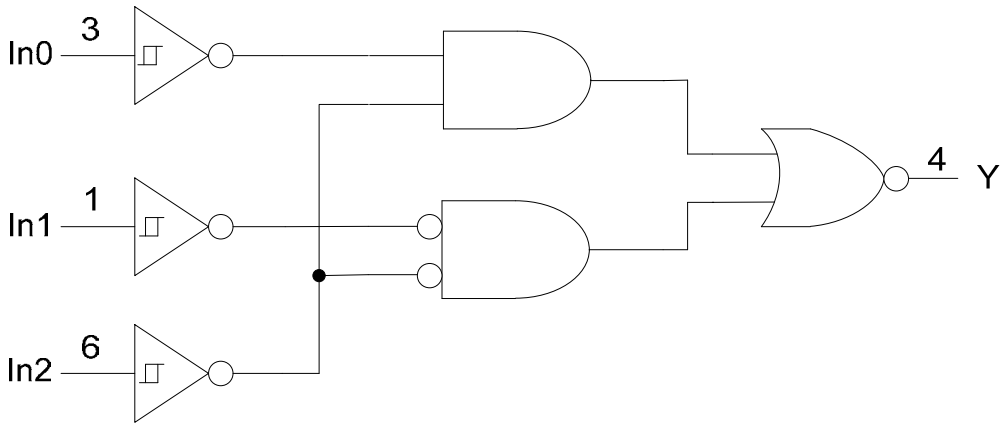
Pin Descriptions

Pin Name	Function
IN1	Data Input
GND	Ground
IN0	Data Input
Y	Data Output
V_{CC}	Supply Voltage
IN2	Data Input

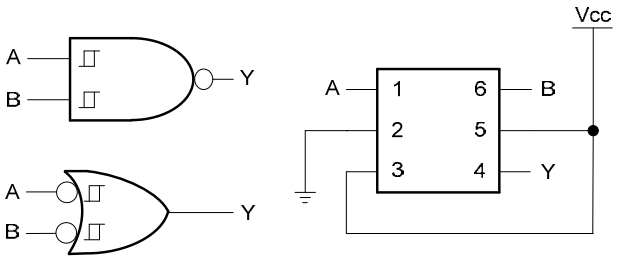
Logic Diagram



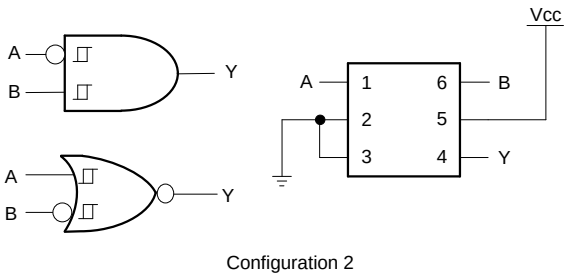
Function Table

Inputs			Output
IN2	IN1	IN0	Y
L	L	L	L
L	L	H	H
L	H	L	L
L	H	H	H
H	L	L	H
H	L	H	H
H	H	L	L
H	H	H	L

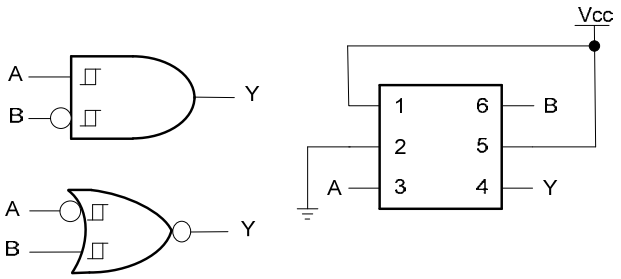
Logic Configurations



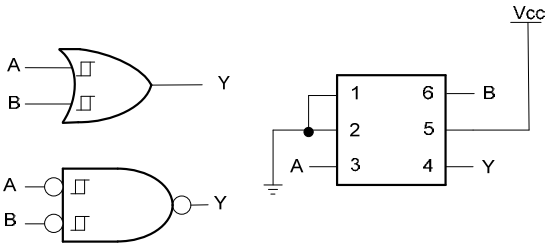
Configuration 1
2-Input NAND Gate
2-Input OR Gate with Both Inputs Inverted



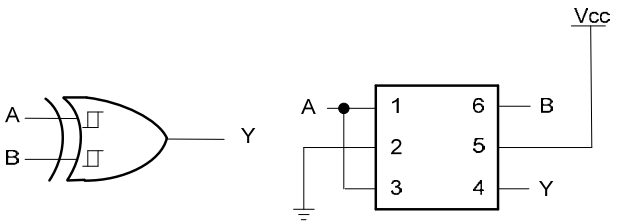
Configuration 2
2-Input AND Gate with A Input Inverted
2-Input NOR Gate with B input Inverted



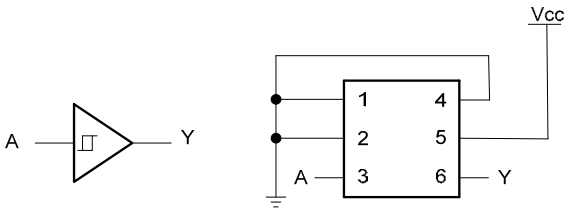
Configuration 3
2-Input AND Gate with B Input Inverted
2-Input NOR Gate with A Input Inverted



Configuration 4
2-Input OR Gate
2-Input NAND Gate with Both Inputs Inverted



Configuration 5
2-Input XOR Gate



Configuration 6
Buffer

Function Selection Table	
Logic Function	**Configuration**
2-input NAND	1
2-input NAND with both inputs inverted	4
2-input AND with inverted input	2, 3
2-input NOR with inverted input	2, 3
2-input OR	4
2-input OR with both inputs inverted	1
2-input XOR	5
1-input Buffer	6

Absolute Maximum Ratings (Note 4)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	200	V
V_{CC}	Supply Voltage Range	-0.5 to 6.5	V
V_I	Input Voltage Range	-0.5 to 6.5	V
V_O	Voltage applied to output in high impedance or I_{OFF} state	-0.5 to 6.5	V
V_O	Voltage applied to output in high or low state	-0.3 to V_{CC} +0.5	V
I_{IK}	Input Clamp Current $V_I < 0$	-50	mA
I_{OK}	Output Clamp Current	-50	mA
I_O	Continuous output current	±50	mA
	Continuous current through Vdd or GND	±100	mA
T_J	Operating Junction Temperature	-40 to +150	°C
T_{STG}	Storage Temperature	-65 to +150	°C

Notes: 4. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

Recommended Operating Conditions (Note 5)

Symbol	Parameter		Min	Max	Unit
V_{CC}	Operating Voltage	Operating	1.65	5.5	V
		Data retention only	1.5		V
V_I	Input Voltage		0	5.5	V
V_O	Output Voltage		0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 1.65V		-4	mA
		V_{CC} = 2.3V		-8	
		V_{CC} = 3V		-16	
				-24	
		V_{CC} = 4.5V		-32	
I_{OL}	Low-level output current	V_{CC} = 1.65V		4	mA
		V_{CC} = 2.3V		8	
		V_{CC} = 3V		16	
				24	
		V_{CC} = 4.5V		32	
Δt/ΔV	Input transition rise or fall rate	V_{CC} = 1.8V ± 0.15V, 2.5V ± 0.2V		20	ns/V
		V_{CC} = 3.3V ± 0.3V		10	
		V_{CC} = 5V ± 0.5V		5	
T_A	Operating free-air temperature		-40	+125	ºC

Notes: 5. Unused inputs should be held at V_{CC} or Ground.

Electrical Characteristics T_A = -40°C to +85°C (All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
V_{T+}	Positive-going input threshold voltage		1.65V	0.70		1.20	
			2.3V	1.11		1.60	
			3V	1.50		2.00	
			4.5V	2.16		2.74	
			5.5V	2.61		3.33	
V_{T-}	Negative-going input threshold voltage		1.65V	0.30		0.72	
			2.3V	0.58		1.00	
			3V	0.80		1.30	
			4.5V	1.21		1.95	
			5.5V	1.45		2.35	
ΔV_T	Hysteresis (V_{T+} - V_{T-})		1.65V	0.30		0.62	
			2.3V	0.40		0.80	
			3V	0.35		1.00	
			4.5V	0.55		1.10	
			5.5V	0.60		1.20	
V_{OH}	High Level Output Voltage	I_{OH} = -100µA	1.65V to 5.5V	V_{CC} – 0.1			V
		I_{OH} = -4mA	1.65V	1.2			
		I_{OH} = -8mA	2.3V	1.9			
		I_{OH} = -16mA	3V	2.4			
		I_{OH} = -24mA		2.3			
		I_{OH} = -32mA	4.5V	3.8			
V_{OL}	High-level Input Voltage	I_{OL} = 100µA	1.65V to 5.5V			0.1	V
		I_{OL} = 4mA	1.65V			0.45	
		I_{OL} = 8mA	2.3V			0.3	
		I_{OL} = 16mA	3V			0.4	
		I_{OL} = 24mA				0.55	
		I_{OL} = 32mA	4.5			0.55	
I_I	Input Current	V_I = 5.5V or GND	0 to 5.5V			± 5	µA
I_{OFF}	Power Down Leakage Current	V_I or V_O = 5.5V	0			± 10	µA
I_{CC}	Supply Current	V_I = 5.5V of GND I_O=0	1.65V to 5.5V			10	µA
ΔI_{CC}	Additional Supply Current	One input at V_{CC} -0.6V Other inputs at V_{CC} or GND	3V to 5.5V			500	µA

Electrical Characteristics T_A = -40°C to +125°C (All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
V_{T+}	Positive-going input threshold voltage		1.65V	0.70		1.20	
			2.3V	1.11		1.60	
			3V	1.50		2.00	
			4.5V	2.16		2.74	
			5.5V	2.61		3.33	
V_{T-}	Negative-going input threshold voltage		1.65V	0.30		0.75	
			2.3V	0.58		1.03	
			3V	0.80		1.33	
			4.5V	1.21		1.95	
			5.5V	1.45		2.35	
ΔV_T	Hysteresis (V_{T+} - V_{T-})		1.65V	0.30		0.62	
			2.3V	0.37		0.80	
			3V	0.32		1.00	
			4.5V	0.50		1.20	
			5.5V	0.55		1.40	
V_{OH}	High Level Output Voltage	I_{OH} = -100µA	1.65V to 5.5V	V_{CC} -0.1			V
		I_{OH} = -4mA	1.65V	0.95			
		I_{OH} = -8mA	2.3V	1.7			
		I_{OH} = -16mA	3V	1.9			
		I_{OH} = -24mA		2.0			
		I_{OH} = -32mA	4.5V	3.4			
V_{OL}	High-level Input Voltage	I_{OL} = 100µA	1.65V to 5.5V			0.1	V
		I_{OL} = 4mA	1.65V			0.7	
		I_{OL} = 8mA	2.3V			0.45	
		I_{OL} = 16mA	3V			0.6	
		I_{OL} = 24mA				0.8	
		I_{OL} = 32mA	4.5			0.8	
I_I	Input Current	V_I = 5.5V or GND	0 to 5.5V			± 100	µA
I_{OFF}	Power Down Leakage Current	V_I or V_O = 5.5V	0			± 200	µA
I_{CC}	Supply Current	V_I = 5.5V of GND I_O=0	1.65V to 5.5V			200	µA
ΔI_{CC}	Additional Supply Current	One input at V_{CC} -0.6V Other inputs at V_{CC} or GND	3V to 5.5V			5000	µA

Electrical Characteristics (All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V_{CC}	Min	Typ	Max	Unit
C_I	Input Capacitance	V_I = V_{CC} – or GND	3.3		3.5		pF
θ_{JA}	Thermal Resistance Junction-to-Ambient	SOT26	(Note 6)		204		°C/W
		SOT363			371		
		X2-DFN1410-6			430		
		X2-DFN1010-6			510		
θ_{JC}	Thermal Resistance Junction-to-Case	SOT26	(Note 6)		52		°C/W
		SOT363			143		
		X2-DFN1410-6			190		
		X2-DFN1010-6			250		

Notes: 6. Test condition for SOT26, SOT363, X2-DFN1410-6 and X2-DFN1010-6: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

Switching Characteristics

T_A = -40°C to +85°C, CL = 30 or 50pF as noted (see Figure 1)

Parameter	From (Input)	TO (OUTPUT)	V_{CC} = 1.8V ± 0.15V		V_{CC} = 2.5V ± 0.2V		V_{CC} = 3.3V ± 0.3V		V_{CC} = 5V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	Any	Y	1.0	14.4	0.7	8.3	0.7	6.3	0.7	5.1	ns

T_A = -40°C to +125°C, CL = 30 or 50pF as noted (see Figure 1)

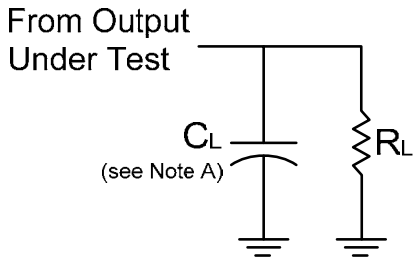
Parameter	From (Input)	TO (OUTPUT)	V_{CC} = 1.8V ± 0.15V		V_{CC} = 2.5V ± 0.2V		V_{CC} = 3.3V ± 0.3V		V_{CC} = 5V ± 0.5V		Unit
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{pd}	Any	Y	1.0	18.0	0.7	10.4	0.7	7.9	0.7	6.4	ns

Operating Characteristics

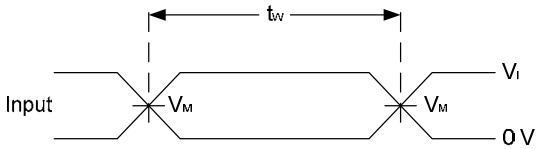
T_A = +25°C

Parameter		Test Conditions	V_{CC} = 1.8V	V_{CC} = 2.5V	V_{CC} = 3.3V	V_{CC} = 5V	Unit
			Typ.	Typ.	Typ.	Typ.	
C_{pd}	Power dissipation capacitance	f = 10 MHz	22	22	23	24	pF

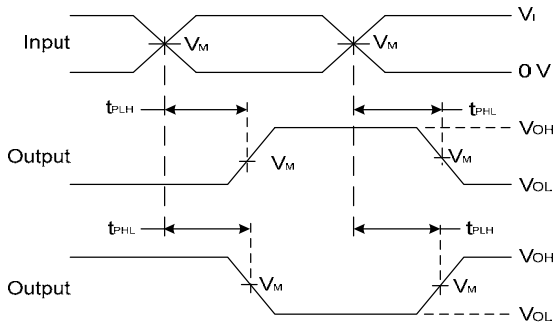
Parameter Measurement Information



V_{CC}	Inputs		V_M	C_L	R_L
	V_I	t_r/t_f			
1.8V±0.15V	V_{CC}	≤2ns	$V_{CC}/2$	30pF	1KΩ
2.5V±0.2V	V_{CC}	≤2ns	$V_{CC}/2$	30pF	500Ω
3.3V±0.3V	3V	≤2.5ns	1.5V	50pF	500Ω
5V±0.5V	V_{CC}	≤2.5ns	$V_{CC}/2$	50pF	500Ω



Voltage Waveform
Pulse Duration

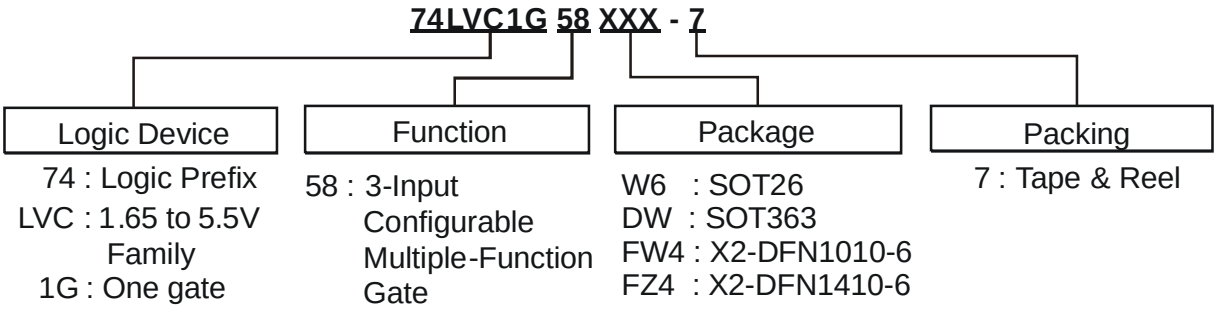


Voltage Waveform
Propagation Delay Times
Inverting and Non Inverting Outputs

Figure 1. Load Circuit and Voltage Waveforms

Notes:
A. Includes test lead and test apparatus capacitance.
B. All pulses are supplied at pulse repetition rate ≤ 10 MHz
C. Inputs are measured separately one transition per measurement
D. t_{PLH} and t_{PHL} are the same as t_{PD}

Ordering Information

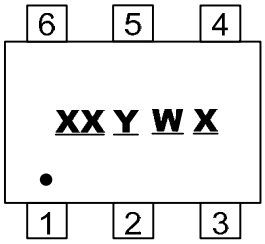


Device	Package Code	Packaging (Note 7)	7" Tape and Reel	
			Quantity	Part Number Suffix
74LVC1G58W6-7	W6	SOT26	3000/Tape & Reel	-7
74LVC1G58DW-7	DW	SOT363	3000/Tape & Reel	-7
74LVC1G58FW4-7	FW4	X2-DFN1010-6	5000/Tape & Reel	-7
74LVC1G58FZ4-7	FZ4	X2-DFN1410-6	5000/Tape & Reel	-7

Notes: 7. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

Marking Information

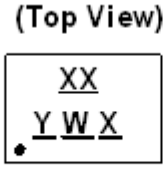
(1) SOT26, SOT363



XX : Identification code
Y : Year 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week
X : A~Z : Internal Code

Part Number	Package	Identification Code
74LVC1G58W6	SOT26	TX
74LVC1G58DW	SOT363	TX

(2) X2-DFN1010-6, X2-DFN1410-6

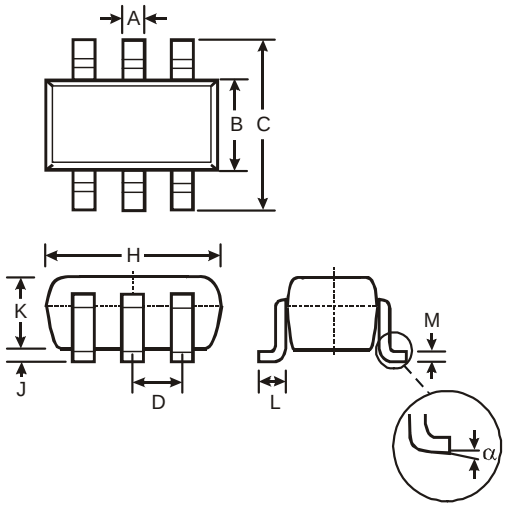


XX : Identification Code
Y : Year : 0~9
W : Week : A~Z : 1~26 week;
a~z : 27~52 week; z represents
52 and 53 week
X : A~Z : Internal code

Part Number	Package	Identification Code
74LVC1G58FW4	X2-DFN1010-6	TX
74LVC1G58FZ4	X2-DFN1410-6	TX

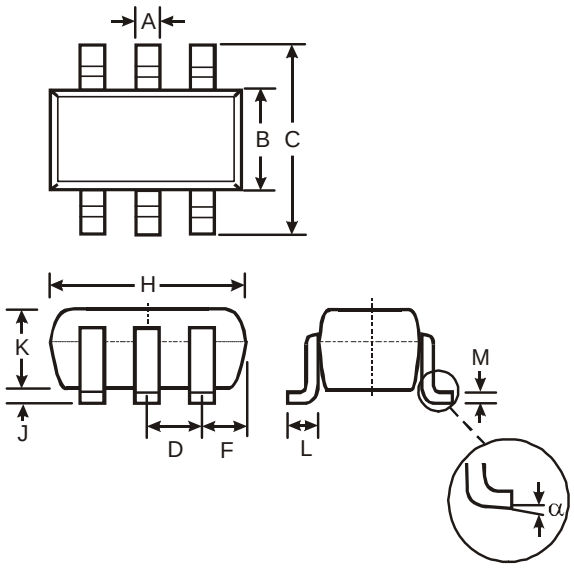
Package Outline Dimensions (All Dimensions in mm)

(1) SOT26



SOT26			
Dim	**Min**	**Max**	**Typ**
A	0.35	0.50	0.38
B	1.50	1.70	1.60
C	2.70	3.00	2.80
D	—	—	0.95
H	2.90	3.10	3.00
J	0.013	0.10	0.05
K	1.00	1.30	1.10
L	0.35	0.55	0.40
M	0.10	0.20	0.15
α	0°	8°	—
All Dimensions in mm			

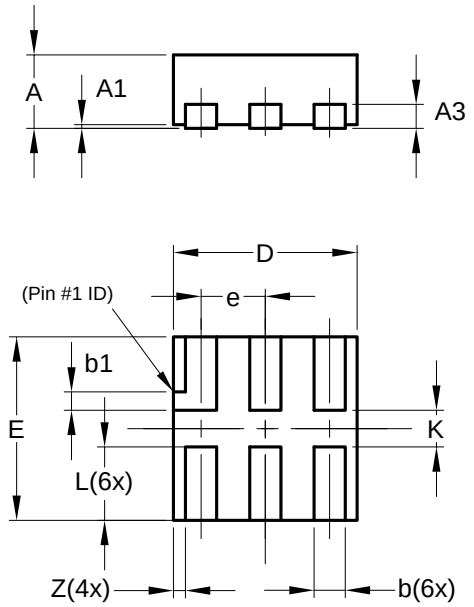
(2) SOT363



SOT363		
Dim	**Min**	**Max**
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

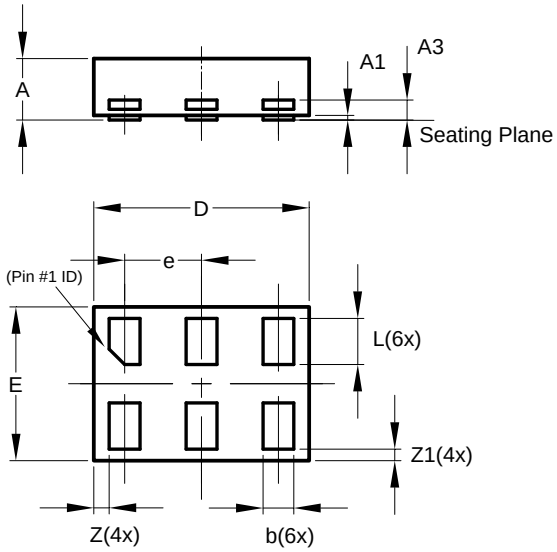
Package Outline Dimensions (All Dimensions in mm)

(3) X2-DFN1010-6



X2-DFN1010-6			
Dim	**Min**	**Max**	**Typ**
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.14	0.20	0.17
b1	0.05	0.15	0.10
D	0.95	1.05	1.00
E	0.95	1.05	1.00
e	—	—	0.35
L	0.35	0.45	0.40
K	0.15	—	—
Z	—	—	0.065
All Dimensions in mm			

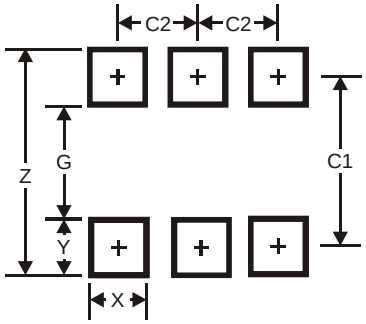
(4) X2-DFN1410-6



X2-DFN1410-6			
Dim	**Min**	**Max**	**Typ**
A	—	0.40	0.39
A1	0.00	0.05	0.02
A3	—	—	0.13
b	0.15	0.25	0.20
D	1.35	1.45	1.40
E	0.95	1.05	1.00
e	—	—	0.50
L	0.25	0.35	0.30
Z	—	—	0.10
Z1	0.045	0.105	0.075
All Dimensions in mm			

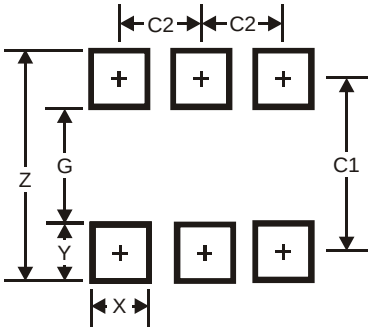
Suggest Pad Layout

(1) SOT26



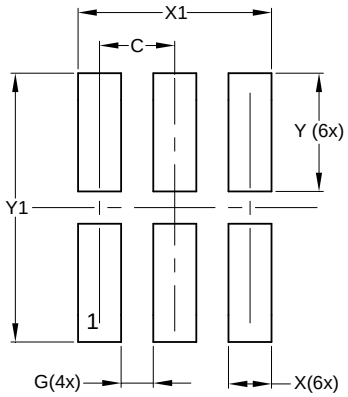
Dimensions	Value (in mm)
Z	3.20
G	1.60
X	0.55
Y	0.80
C1	2.40
C2	0.95

(2) SOT363



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65

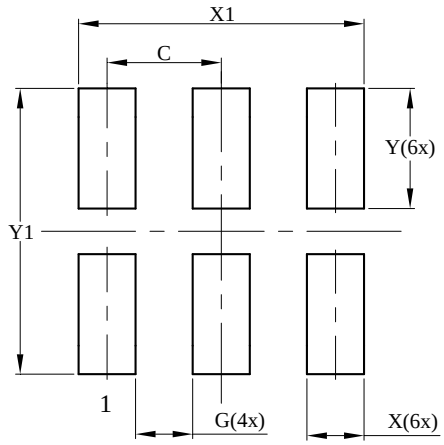
(3) X2-DFN1010-6



Dimensions	Value (in mm)
C	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

Suggest Pad Layout

(4) X2-DFN1410-6



Dimensions	Value (in mm)
C	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250

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